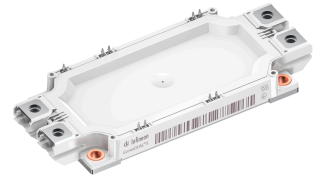


Final datasheet

EconoDUAL™3 module with Trench/Fieldstop IGBT4 and emitter controlled HE diode and PressFIT / NTC / current sense shunt

Features

- Electrical features
 - $V_{CES} = 1200\text{ V}$
 - $I_{C\text{ nom}} = 300\text{ A} / I_{CRM} = 600\text{ A}$
 - Integrated current sensor
 - Low $V_{CE,sat}$
 - $T_{vj,op} = 150^{\circ}\text{C}$
 - $V_{CE,sat}$ with positive temperature coefficient
- Mechanical features
 - PressFIT contact technology
 - Pre-applied thermal interface material
 - Isolated base plate
 - High power density



Potential applications

- Servo drives
- High-power converters
- Motor drives
- UPS systems
- Wind turbines

Product validation

- Qualified for industrial applications according to the relevant tests of IEC 60747, 60749 and 60068

Description

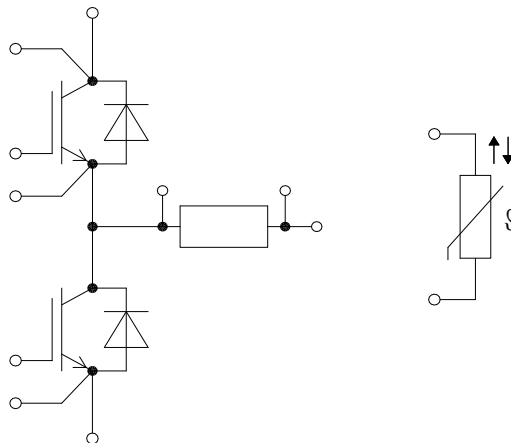


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1 Package

1 Package

Table 1 Insulation coordination

Parameter	Symbol	Note or test condition	Values	Unit
Isolation test voltage	V_{ISOL}	RMS, $f = 50$ Hz, $t = 1$ min	2.5	kV
Isolation test voltage NTC	$V_{ISOL(NTC)}$	RMS, $f = 50$ Hz, $t = 1$ min	2.5	kV
Material of module baseplate			Cu	
Internal isolation		basic insulation (class 1, IEC 61140)	Al_2O_3	
Creepage distance	$d_{Creep\ nom}$	terminal to baseplate, nom., (PD2, IEC 60664-1, Ed. 3.0)	> 15	mm
Creepage distance	$d_{Creep\ min}$	terminal to baseplate, min., (PD2, IEC 60664-1, Ed. 3.0)	14.7	mm
Creepage distance	$d_{Creep\ nom}$	terminal to terminal, nom., (PD2, IEC 60664-1, Ed. 3.0)	12.1	mm
Creepage distance	$d_{Creep\ min}$	terminal to terminal, min., (PD2, IEC 60664-1, Ed. 3.0)	11.5	mm
Clearance	$d_{Clear\ nom}$	terminal to baseplate, nom.	> 12.5	mm
Clearance	$d_{Clear\ min}$	terminal to baseplate, min.	12.5	mm
Clearance	$d_{Clear\ nom}$	terminal to terminal, nom.	10.0	mm
Clearance	$d_{Clear\ min}$	terminal to terminal, min.	9.6	mm
Comparative tracking index	CTI		> 200	
Relative thermal index (electrical)	RTI	housing	140	°C

Table 2 Characteristic values

Parameter	Symbol	Note or test condition	Values			Unit
			Min.	Typ.	Max.	
Stray inductance module	L_{sCE}			20		nH
Module lead resistance, terminals - chip	$R_{CC'+EE'}$	$T_H = 25$ °C, per switch		1		mΩ
Storage temperature	T_{stg}		-40		125	°C
Maximum baseplate operation temperature	T_{BPmax}				125	°C
Mounting torque for module mounting	M	- Mounting according to valid application note	M5, Screw	3	6	Nm
Terminal connection torque	M	- Mounting according to valid application note	M6, Screw	3	6	Nm
Weight	G			345		g

Note: Storage and shipment of modules with TIM => see AN2012-07

2 IGBT, Inverter

Table 3 Maximum rated values

Parameter	Symbol	Note or test condition		Values	Unit
Collector-emitter voltage	V_{CES}		$T_{vj} = 25\text{ °C}$	1200	V
Continuous DC collector current	I_{CDC}	$T_{vj\text{ max}} = 175\text{ °C}$	$T_H = 70\text{ °C}$	300	A
Repetitive peak collector current	I_{CRM}	t_p limited by $T_{vj\text{ op}}$		600	A
Gate-emitter peak voltage	V_{GES}			±20	V

Table 4 Characteristic values

Parameter	Symbol	Note or test condition		Values			Unit
				Min.	Typ.	Max.	
Collector-emitter saturation voltage	$V_{CE\text{ sat}}$	$I_C = 300\text{ A}$, $V_{GE} = 15\text{ V}$	$T_{vj} = 25\text{ °C}$		1.75	2.10	V
			$T_{vj} = 125\text{ °C}$		2.00		
			$T_{vj} = 150\text{ °C}$		2.05		
Gate threshold voltage	V_{GETh}	$I_C = 11.5\text{ mA}$, $V_{CE} = V_{GE}$, $T_{vj} = 25\text{ °C}$		5.25	5.80	6.45	V
Gate charge	Q_G	$V_{GE} = \pm 15\text{ V}$			2.25		μC
Internal gate resistor	R_{Gint}	$T_{vj} = 25\text{ °C}$			2.5		Ω
Input capacitance	C_{ies}	$f = 1000\text{ kHz}$, $T_{vj} = 25\text{ °C}$, $V_{CE} = 25\text{ V}$, $V_{GE} = 0\text{ V}$			18.5		nF
Reverse transfer capacitance	C_{res}	$f = 1000\text{ kHz}$, $T_{vj} = 25\text{ °C}$, $V_{CE} = 25\text{ V}$, $V_{GE} = 0\text{ V}$			1.05		nF
Collector-emitter cut-off current	I_{CES}	$V_{CE} = 1200\text{ V}$, $V_{GE} = 0\text{ V}$	$T_{vj} = 25\text{ °C}$			3	mA
Gate-emitter leakage current	I_{GES}	$V_{CE} = 0\text{ V}$, $V_{GE} = 20\text{ V}$, $T_{vj} = 25\text{ °C}$				400	nA
Turn-on delay time (inductive load)	t_{don}	$I_C = 300\text{ A}$, $V_{CC} = 600\text{ V}$, $V_{GE} = \pm 15\text{ V}$, $R_{Gon} = 1.3\text{ Ω}$	$T_{vj} = 25\text{ °C}$		0.150		μs
			$T_{vj} = 125\text{ °C}$		0.170		
			$T_{vj} = 150\text{ °C}$		0.170		
Rise time (inductive load)	t_r	$I_C = 300\text{ A}$, $V_{CC} = 600\text{ V}$, $V_{GE} = \pm 15\text{ V}$, $R_{Gon} = 1.3\text{ Ω}$	$T_{vj} = 25\text{ °C}$		0.050		μs
			$T_{vj} = 125\text{ °C}$		0.050		
			$T_{vj} = 150\text{ °C}$		0.050		
Turn-off delay time (inductive load)	t_{doff}	$I_C = 300\text{ A}$, $V_{CC} = 600\text{ V}$, $V_{GE} = \pm 15\text{ V}$, $R_{Goff} = 1.3\text{ Ω}$	$T_{vj} = 25\text{ °C}$		0.350		μs
			$T_{vj} = 125\text{ °C}$		0.450		
			$T_{vj} = 150\text{ °C}$		0.480		

(table continues...)

Table 4 (continued) Characteristic values

Parameter	Symbol	Note or test condition	Values			Unit
			Min.	Typ.	Max.	
Fall time (inductive load)	t_f	$I_C = 300\text{ A}$, $V_{CC} = 600\text{ V}$, $V_{GE} = \pm 15\text{ V}$, $R_{Goff} = 1.3\ \Omega$	$T_{vj} = 25\text{ °C}$	0.100		μs
			$T_{vj} = 125\text{ °C}$	0.200		
			$T_{vj} = 150\text{ °C}$	0.240		
Turn-on energy loss per pulse	E_{on}	$I_C = 300\text{ A}$, $V_{CC} = 600\text{ V}$, $L_\sigma = 35\text{ nH}$, $V_{GE} = \pm 15\text{ V}$, $R_{Gon} = 1.3\ \Omega$, $di/dt = 5550\text{ A}/\mu\text{s}$ ($T_{vj} = 150\text{ °C}$)	$T_{vj} = 25\text{ °C}$	18		mJ
			$T_{vj} = 125\text{ °C}$	30		
			$T_{vj} = 150\text{ °C}$	34		
Turn-off energy loss per pulse	E_{off}	$I_C = 300\text{ A}$, $V_{CC} = 600\text{ V}$, $L_\sigma = 35\text{ nH}$, $V_{GE} = \pm 15\text{ V}$, $R_{Goff} = 1.3\ \Omega$, $dv/dt = 3250\text{ V}/\mu\text{s}$ ($T_{vj} = 150\text{ °C}$)	$T_{vj} = 25\text{ °C}$	22		mJ
			$T_{vj} = 125\text{ °C}$	36		
			$T_{vj} = 150\text{ °C}$	40		
SC data	I_{SC}	$V_{GE} \leq 15\text{ V}$, $V_{CC} = 800\text{ V}$, $V_{CEmax} = V_{CES} - L_{sCE} \cdot di/dt$	$t_p \leq 10\ \mu\text{s}$, $T_{vj} = 150\text{ °C}$	1200		A
Thermal resistance, junction to heat sink	R_{thJH}	per IGBT, Valid with IFX pre-applied Thermal Interface Material			0.136	K/W
Temperature under switching conditions	$T_{vj\text{ op}}$		-40		150	°C

3 Diode, Inverter

Table 5 Maximum rated values

Parameter	Symbol	Note or test condition	Values	Unit
Repetitive peak reverse voltage	V_{RRM}	$T_{vj} = 25\text{ °C}$	1200	V
Continuous DC forward current	I_F		300	A
Repetitive peak forward current	I_{FRM}	$t_p = 1\text{ ms}$	600	A
I^2t - value	I^2t	$t_p = 10\text{ ms}$, $V_R = 0\text{ V}$	$T_{vj} = 125\text{ °C}$	A^2s
			$T_{vj} = 150\text{ °C}$	

Table 6 Characteristic values

Parameter	Symbol	Note or test condition	Values			Unit
			Min.	Typ.	Max.	
Forward voltage	V_F	$I_F = 300\text{ A}$, $V_{GE} = 0\text{ V}$	$T_{vj} = 25\text{ °C}$	1.65	2.10	V
			$T_{vj} = 125\text{ °C}$	1.65		
			$T_{vj} = 150\text{ °C}$	1.65		

(table continues...)

Table 6 (continued) Characteristic values

Parameter	Symbol	Note or test condition	Values			Unit
			Min.	Typ.	Max.	
Peak reverse recovery current	I_{RM}	$V_{CC} = 600\text{ V}$, $I_F = 300\text{ A}$, $V_{GE} = -15\text{ V}$, $-di_F/dt = 5550\text{ A}/\mu\text{s}$ ($T_{vj} = 150\text{ °C}$)	$T_{vj} = 25\text{ °C}$	250		A
			$T_{vj} = 125\text{ °C}$	305		
			$T_{vj} = 150\text{ °C}$	320		
Recovered charge	Q_r	$V_{CC} = 600\text{ V}$, $I_F = 300\text{ A}$, $V_{GE} = -15\text{ V}$, $-di_F/dt = 5550\text{ A}/\mu\text{s}$ ($T_{vj} = 150\text{ °C}$)	$T_{vj} = 25\text{ °C}$	31.5		μC
			$T_{vj} = 125\text{ °C}$	61		
			$T_{vj} = 150\text{ °C}$	70		
Reverse recovery energy	E_{rec}	$V_{CC} = 600\text{ V}$, $I_F = 300\text{ A}$, $V_{GE} = -15\text{ V}$, $-di_F/dt = 5550\text{ A}/\mu\text{s}$ ($T_{vj} = 150\text{ °C}$)	$T_{vj} = 25\text{ °C}$	14		mJ
			$T_{vj} = 125\text{ °C}$	26.5		
			$T_{vj} = 150\text{ °C}$	30		
Thermal resistance, junction to heat sink	R_{thJH}	per diode, Valid with IFX pre-applied Thermal Interface Material			0.177	K/W
Temperature under switching conditions	$T_{vj\text{ op}}$		-40		150	°C

4 Shunt

Table 7 Characteristic values

Parameter	Symbol	Note or test condition	Values			Unit
			Min.	Typ.	Max.	
Rated resistance	R_{20}	$T_C = 20\text{ °C}$		0.5		mΩ
Temperature coefficient	TCR	$T_{\text{Range}} = 20...60\text{ °C}$		< 30		ppm/K
Load capacity per shunt resistor	P	$T_C = 80\text{ °C}$			27	W
Operation temperature	$T_{vj\text{ op}}$				200	°C
Thermal resistance, junction to heat sink	R_{thJH}	per shunt, Valid with IFX pre-applied Thermal Interface Material			4.30	K/W

5 NTC-Thermistor

Table 8 Characteristic values

Parameter	Symbol	Note or test condition	Values			Unit
			Min.	Typ.	Max.	
Rated resistance	R_{25}	$T_{NTC} = 25\text{ °C}$		5		kΩ
Deviation of R_{100}	$\Delta R/R$	$T_{NTC} = 100\text{ °C}$, $R_{100} = 493\text{ Ω}$	-5		5	%

(table continues...)



Table 8 (continued) Characteristic values

Parameter	Symbol	Note or test condition	Values			Unit
			Min.	Typ.	Max.	
Power dissipation	P_{25}	$T_{NTC} = 25\text{ °C}$			20	mW
B-value	$B_{25/50}$	$R_2 = R_{25} \exp[B_{25/50}(1/T_2 - 1/(298,15\text{ K}))]$		3375		K
B-value	$B_{25/80}$	$R_2 = R_{25} \exp[B_{25/80}(1/T_2 - 1/(298,15\text{ K}))]$		3411		K
B-value	$B_{25/100}$	$R_2 = R_{25} \exp[B_{25/100}(1/T_2 - 1/(298,15\text{ K}))]$		3433		K

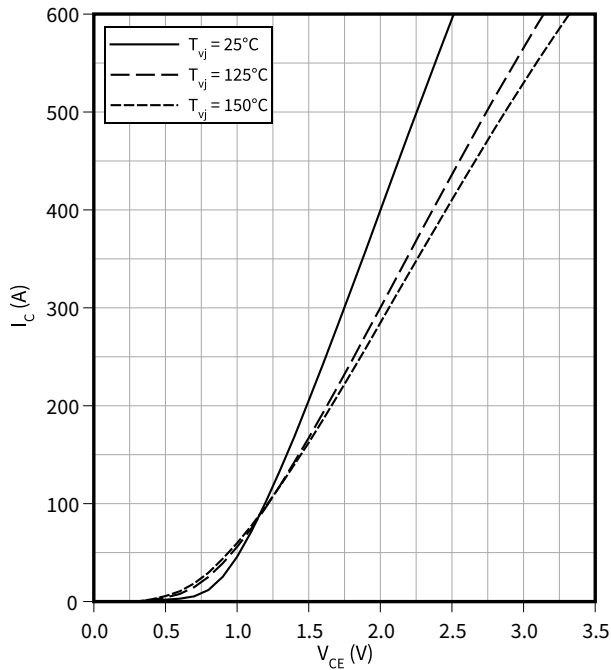
Note: For an analytical description of the NTC characteristics please refer to AN2009-10, chapter 4.

6 Characteristics diagrams

Output characteristic (typical), IGBT, Inverter

$I_C = f(V_{CE})$

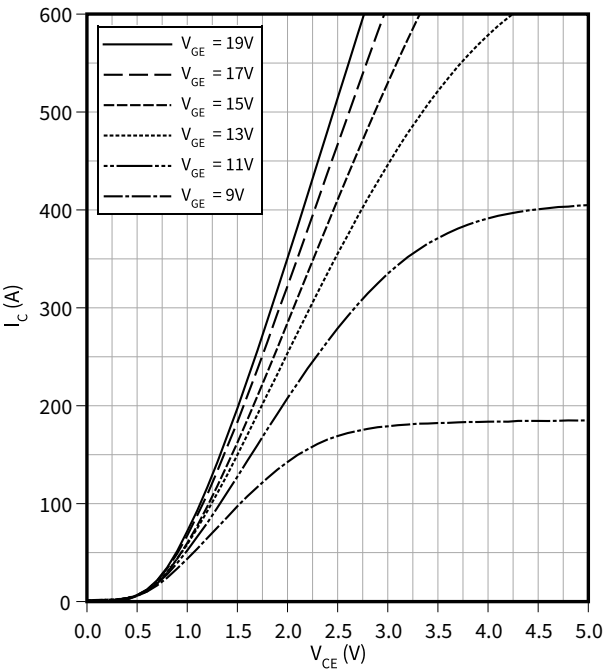
$V_{GE} = 15\text{ V}$



Output characteristic field (typical), IGBT, Inverter

$I_C = f(V_{CE})$

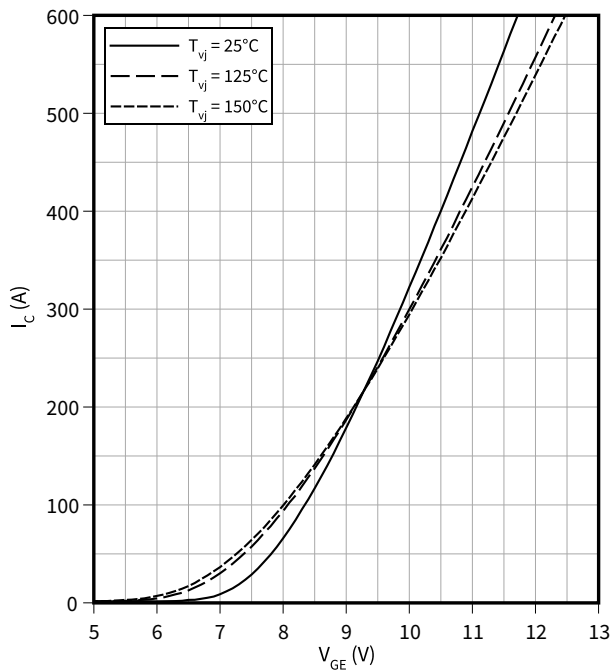
$T_{vj} = 150\text{ °C}$



Transfer characteristic (typical), IGBT, Inverter

$I_C = f(V_{GE})$

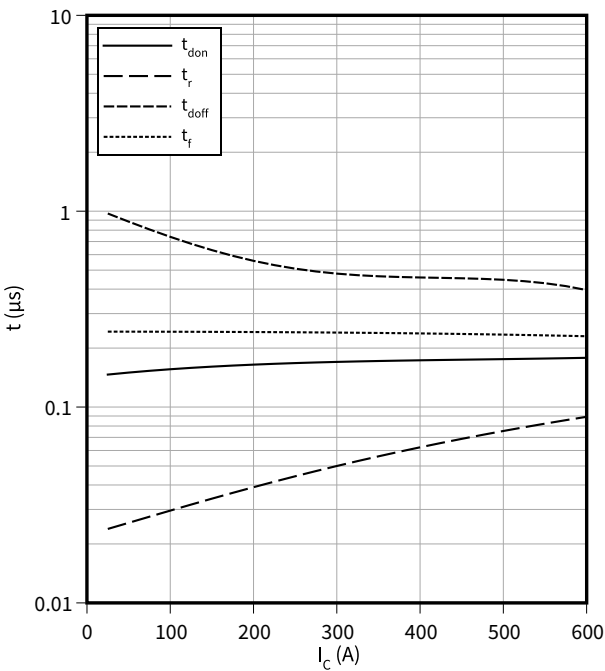
$V_{CE} = 20\text{ V}$



Switching times (typical), IGBT, Inverter

$t = f(I_C)$

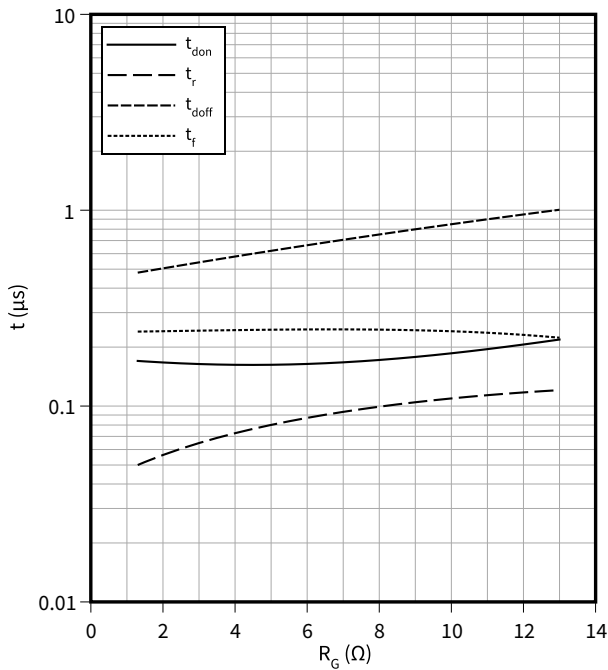
$V_{CC} = 600\text{ V}, R_{Goff} = 1.3\text{ }\Omega, R_{Gon} = 1.3\text{ }\Omega, V_{GE} = \pm 15\text{ V}$



6 Characteristics diagrams

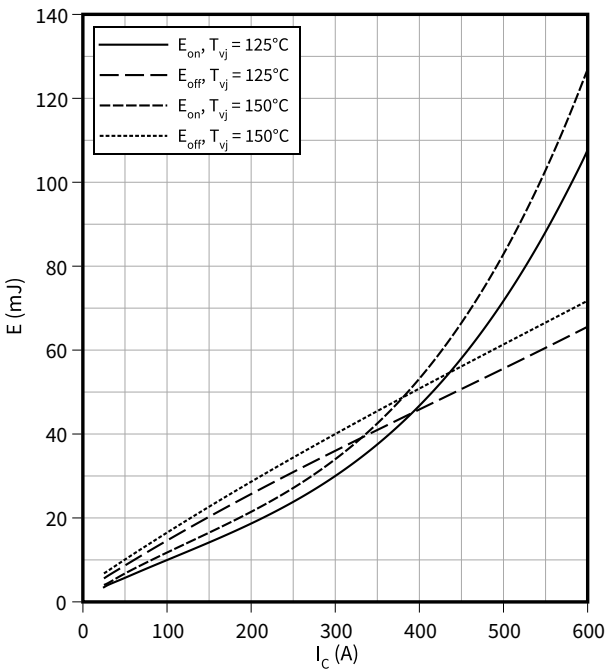
Switching times (typical), IGBT, Inverter

$t = f(R_G)$
 $V_{GE} = \pm 15\text{ V}$, $I_C = 300\text{ A}$, $V_{CC} = 600\text{ V}$



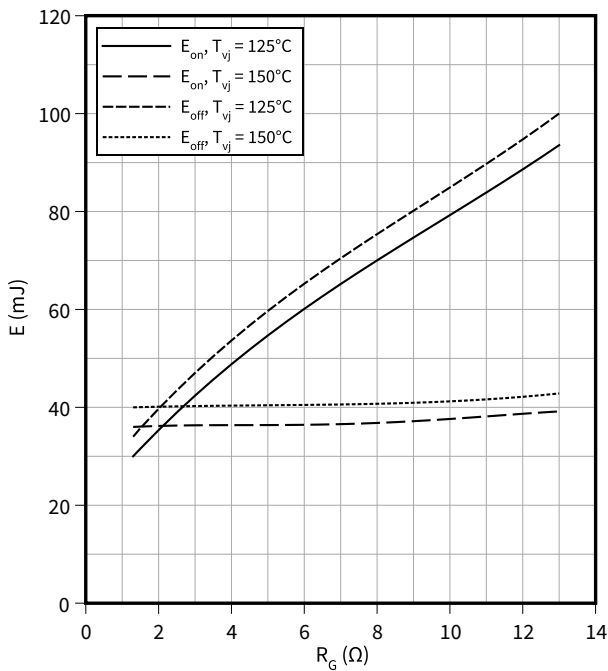
Switching losses (typical), IGBT, Inverter

$E = f(I_C)$
 $R_{Goff} = 1.3\ \Omega$, $R_{Gon} = 1.3\ \Omega$, $V_{GE} = \pm 15\text{ V}$, $V_{CC} = 600\text{ V}$



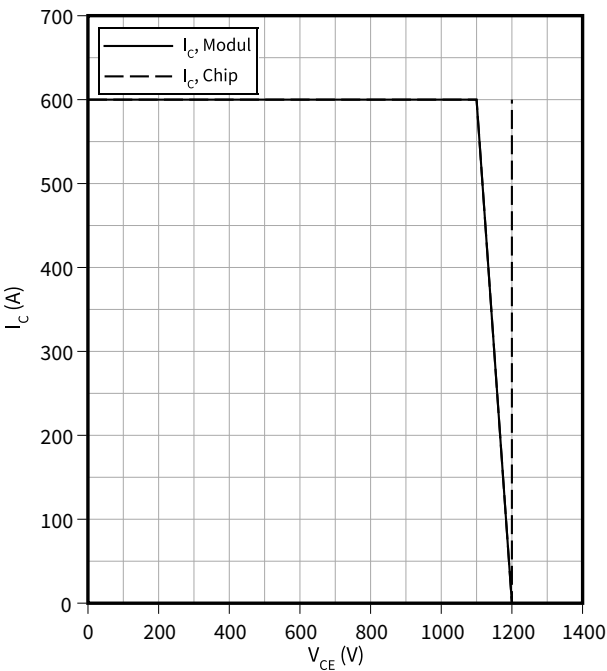
Switching losses (typical), IGBT, Inverter

$E = f(R_G)$
 $I_C = 300\text{ A}$, $V_{GE} = \pm 15\text{ V}$, $V_{CC} = 600\text{ V}$



Reverse bias safe operating area (RBSOA), IGBT, Inverter

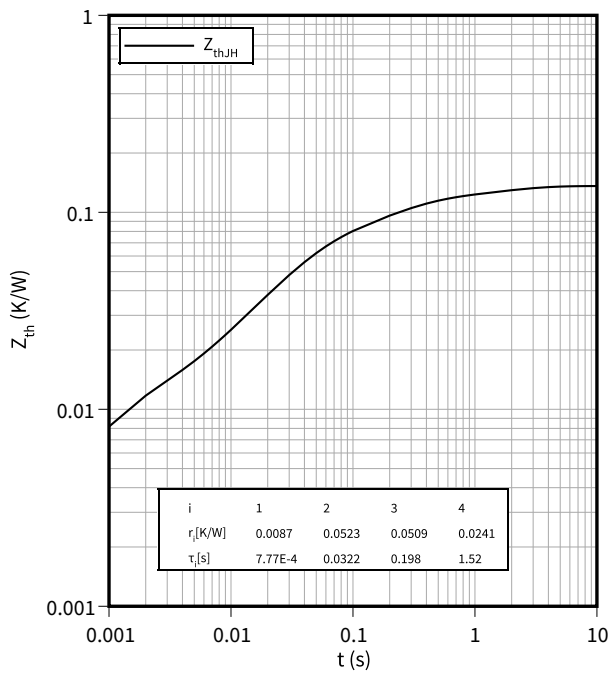
$I_C = f(V_{CE})$
 $R_{Goff} = 1.3\ \Omega$, $V_{GE} = \pm 15\text{ V}$, $T_{vj} = 150\text{ °C}$



6 Characteristics diagrams

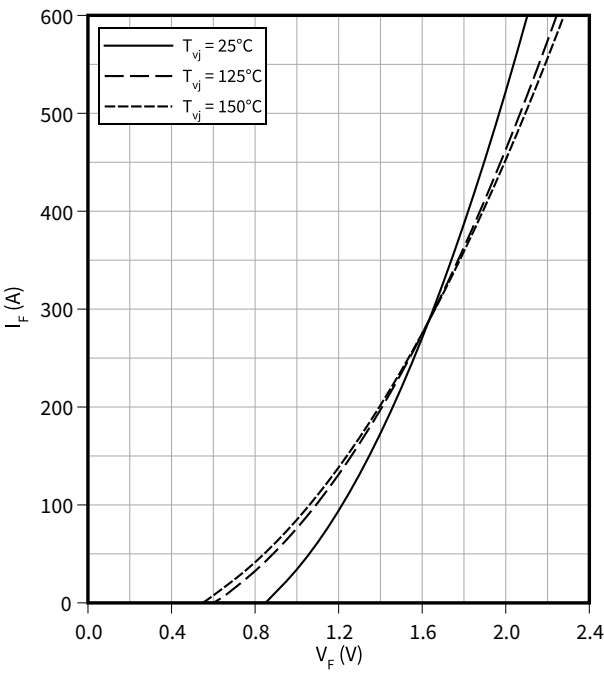
Transient thermal impedance, IGBT, Inverter

$Z_{th} = f(t)$



Forward characteristic (typical), Diode, Inverter

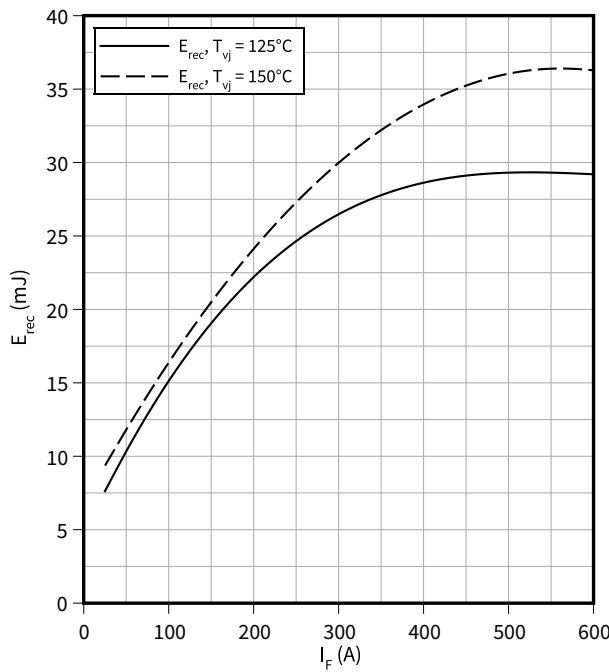
$I_F = f(V_F)$



Switching losses (typical), Diode, Inverter

$E_{rec} = f(I_F)$

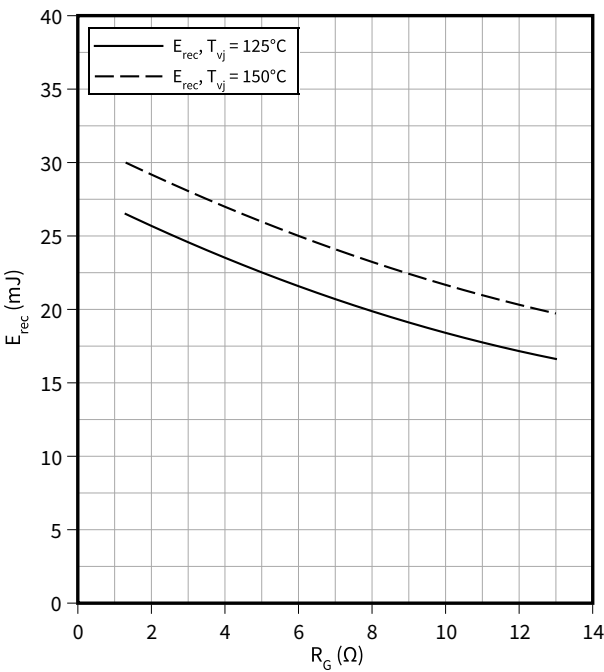
$R_{Gon} = 1.3 \Omega, V_{CC} = 600 V$



Switching losses (typical), Diode, Inverter

$E_{rec} = f(R_G)$

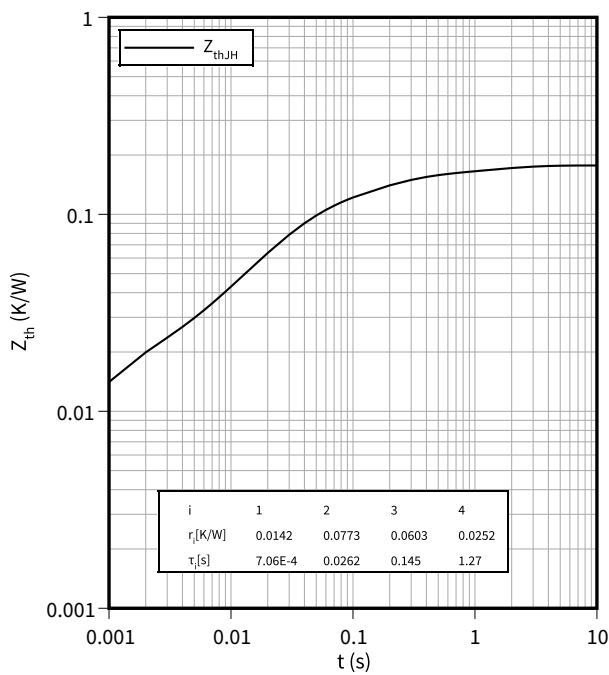
$I_F = 300 A, V_{CC} = 600 V$



6 Characteristics diagrams

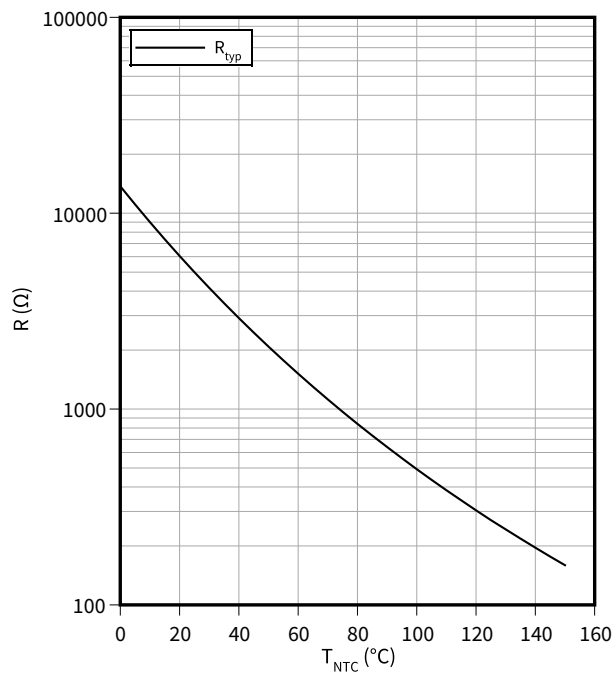
Transient thermal impedance, Diode, Inverter

$Z_{th} = f(t)$



Temperature characteristic (typical), NTC-Thermistor

$R = f(T_{NTC})$



7 Circuit diagram

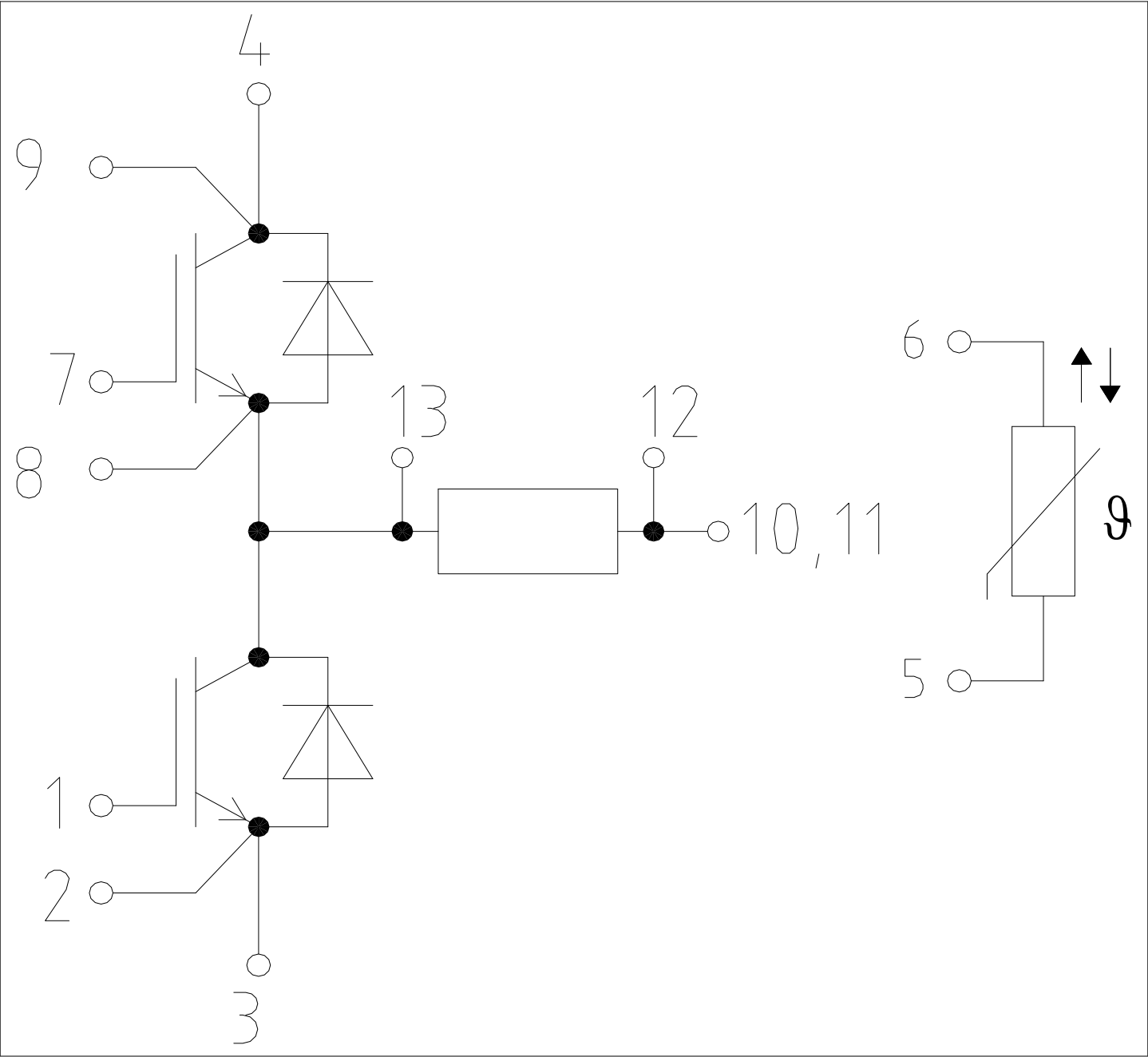


Figure 1

8 Package outlines

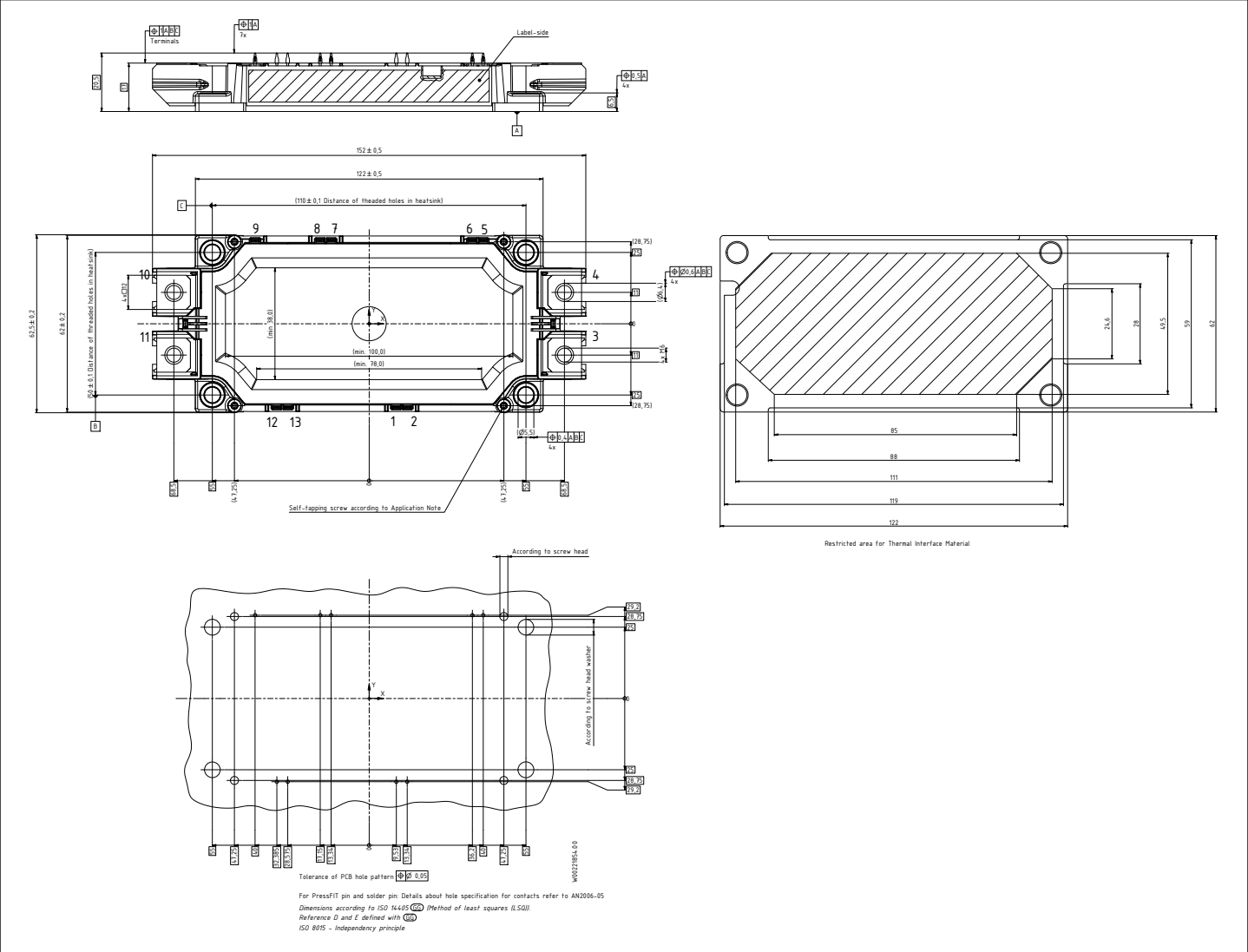


Figure 2

9 Module label code

Module label code			
Code format	Data Matrix		Barcode Code128
Encoding	ASCII text		Code Set A
Symbol size	16x16		23 digits
Standard	IEC24720 and IEC16022		IEC8859-1
Code content	<i>Content</i>	<i>Digit</i>	<i>Example</i>
	Module serial number	1 – 5	71549
	Module material number	6 - 11	142846
	Production order number	12 - 19	55054991
	Date code (production year)	20 – 21	15
	Date code (production week)	22 – 23	30
Example	 71549142846550549911530  71549142846550549911530		

Figure 3



Revision history

Revision history

Document revision	Date of release	Description of changes
V1.0	2017-09-18	Target datasheet
V3.0	2018-04-26	Final datasheet
n/a	2020-09-01	Datasheet migrated to a new system with a new layout and new revision number schema: target or preliminary datasheet = 0.xy; final datasheet = 1.xy
1.10	2024-03-15	Final datasheet

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